



SOT906-2

plastic thermal enhanced very thin quad flat package; no leads; 88 terminals; body 10 x 10 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN88
Package type industry code	HVQFN88
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-8-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	88	-	

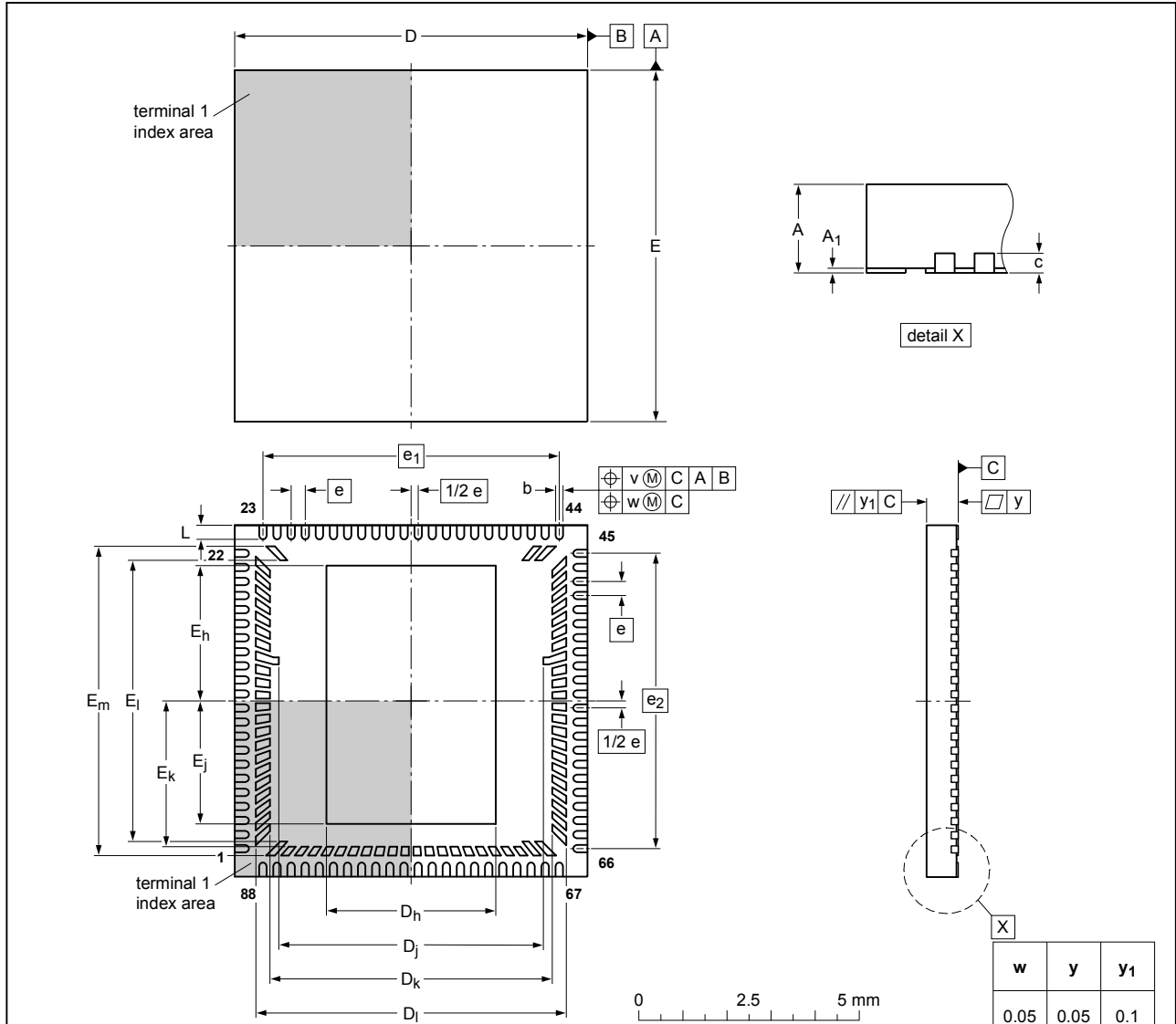


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2. Package outline

HVQFN88: plastic thermal enhanced very thin quad flat package; no leads; 88 terminals; body 10 x 10 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁	b	c	D ⁽¹⁾	D _h	D _j	D _k	D _l	E ⁽¹⁾	E _h	E _j	E _k	E _l	E _m	e	e ₁	e ₂	L	v
mm	1	0.05 0.00	0.25 0.15	0.2	10.1 9.9	4.95 4.65	7.6 7.4	8.1 7.9	8.9 8.7	10.1 9.9	3.90 3.75	3.55 3.40	4.2 4.1	8.1 7.9	8.9 8.7	0.4	8.4	8.4	0.5 0.3	0.1

Notes

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included
2. Mold flash on exposed inner terminals is allowed

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT906-2	---	---	---			05-12-09 06-08-31

Fig. 1. Package outline HVQFN88 (SOT906-2)

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3. Soldering

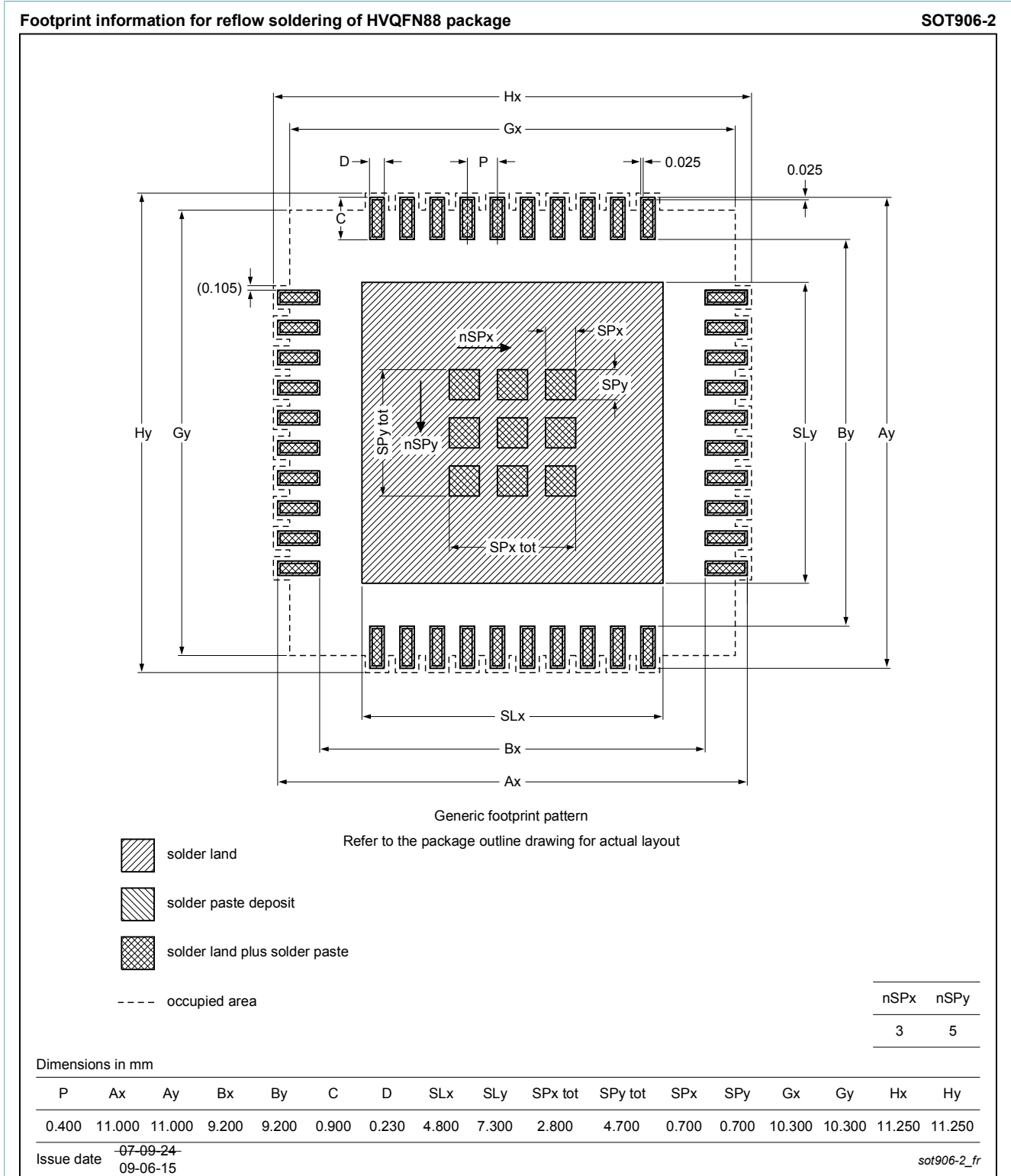


Fig. 2. Reflow soldering footprint for HVQFN88 (SOT906-2)

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4. Legal information

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